

TQ-M4-VSP

- ・ 平滑面をもつ電解銅箔(VSP箔)に超微細表面処理を実施
Very smooth profile ED copper foil (VSP) with very low profile surface treatment.
- ・ 銅箔フルエッチング後のPIの透明性、視認性が良好
Very good performance for transparency and visibility of PI after etching copper foil.
- ・ 超低粗度なラミネート面により、高周波用途への適用も可能
Possible to use high frequency application due to very low profile.

用途/Application

- ・ フレキシブルプリント基板
/Flexible Print Board

構成/Composition



生産拠点/Production Site

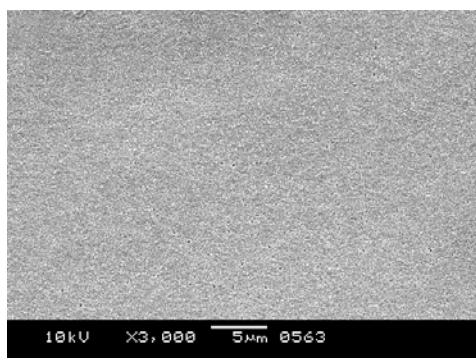
- ・ 日本/Japan

代表的特性値/Representative data

	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm) ^{@FR-4}
TQ-M4-VSP	12	100	0.6	340	9	0.6
	18	148	0.6	340	12	0.7

※表中の数値は代表値です。保証値ではありません。
This is representative data, not guarantee.

ラミ面/Laminate side



レジ面 resist side

